

MakeDevice: Evolving Devices Beyond the Prototype with Jacdac

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Motivation

- Embedded hardware is common
- Prototyping new embedded hardware is easier with toolkits like Arduino¹, micro:bit² and Jacdac³
- Moving beyond a prototype can be *costly* and *complex*⁴
- A "long-tail" of potential devices never reach their full impact⁵
- Can we make the transition from prototype to delivery easier?

Contribution

MakeDevice: A web-based tool that leverages the Jacdac prototyping platform, enabling an end-to-end workflow from a wired desktop prototype to a robust, enclosed device with modules electrically connected via a carrier PCB.

Key features:

- Jacdac modules attached to the PC are automatically detected, arranged on a carrier PCB and electrically routed
- Intuitive drag and drop interface lets users (re)arrange modules
- Automatic generation of Gerber files from the final arrangement, suitable for online PCB fabrication services without modification.
- Various enclosure options are presented to the user, **MakeDevice** automatically generates STL files for 3D printing and SVGs for laser cut press fit boxes or stencils

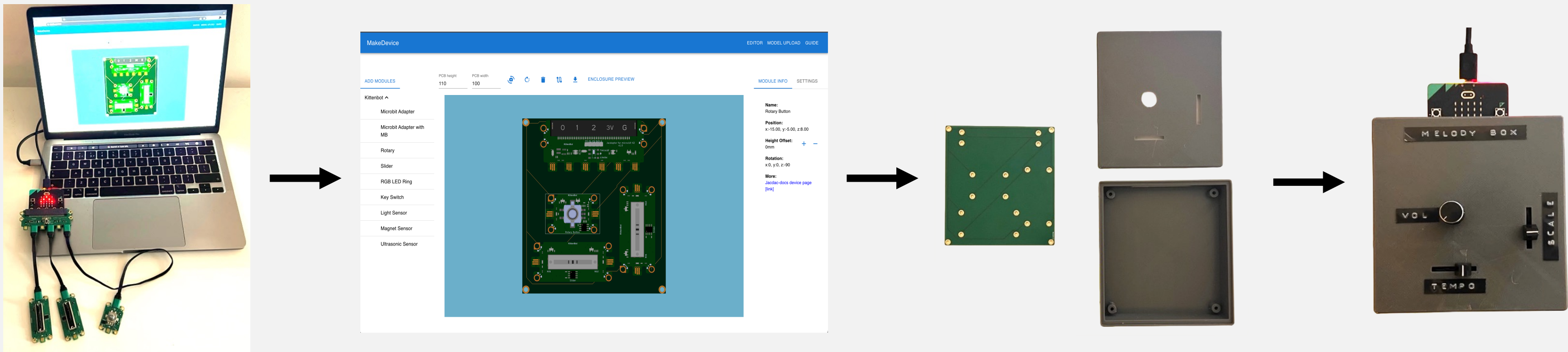
References

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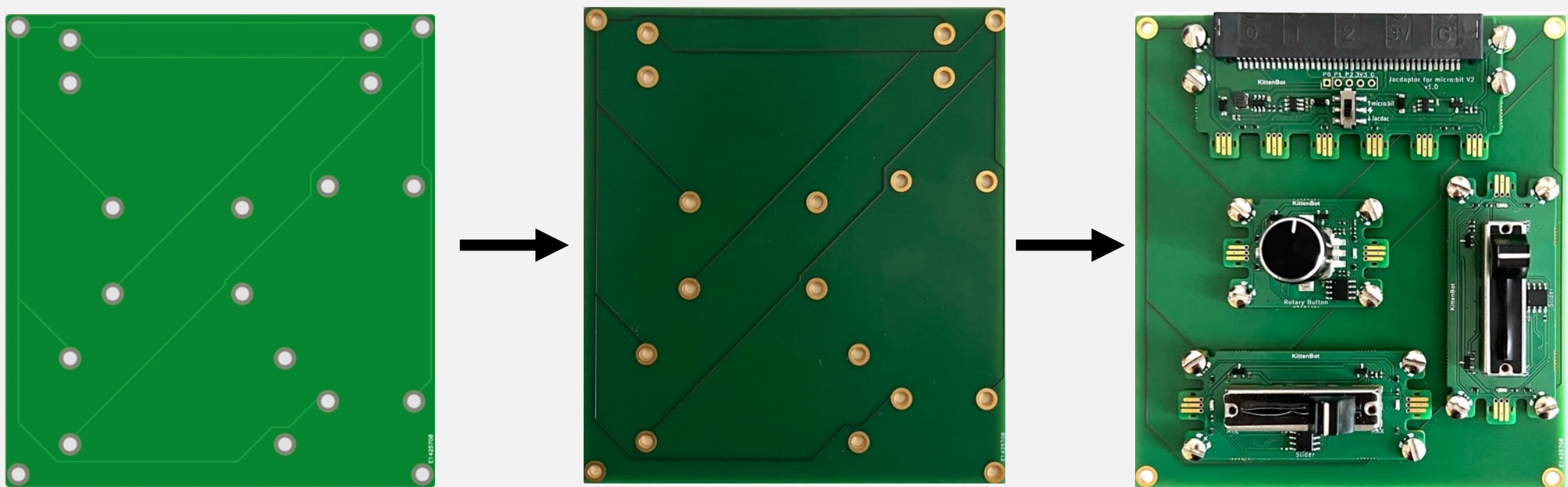
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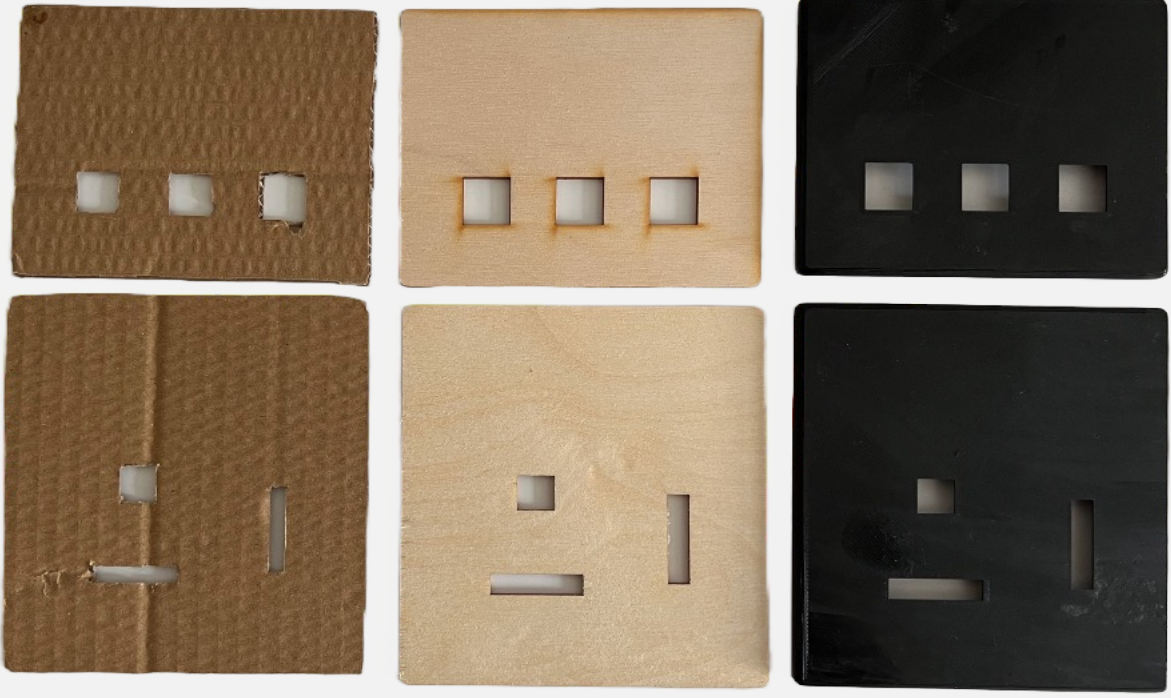
Workflow Overview



Carrier PCB Generation



Enclosure Stencils



Future Work

- User evaluation, exploring the value of **MakeDevice** for various stakeholders: industry, research and home innovators
- Seamless upload of Gerber files and BOMs to PCB fabrication services
- Modification of existing off-the-shelf enclosures to support environmental deployment
- Integration with embedded hardware programming for a complete low-code workflow
- Exploring 3D digital twins of Jacdac modules, reflecting state of Jacdac modules connected in modules shown on screen